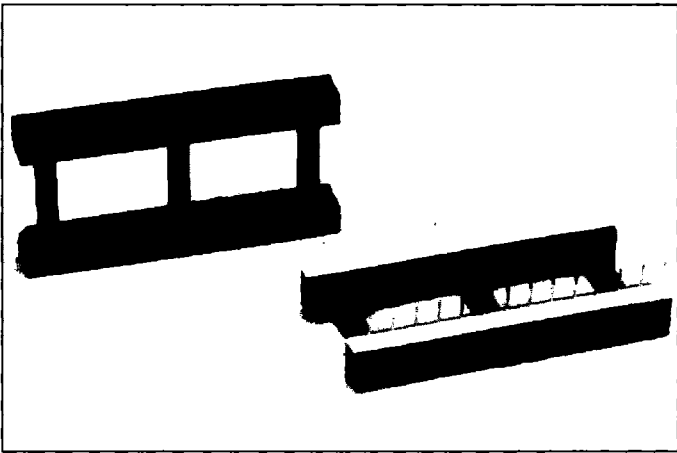


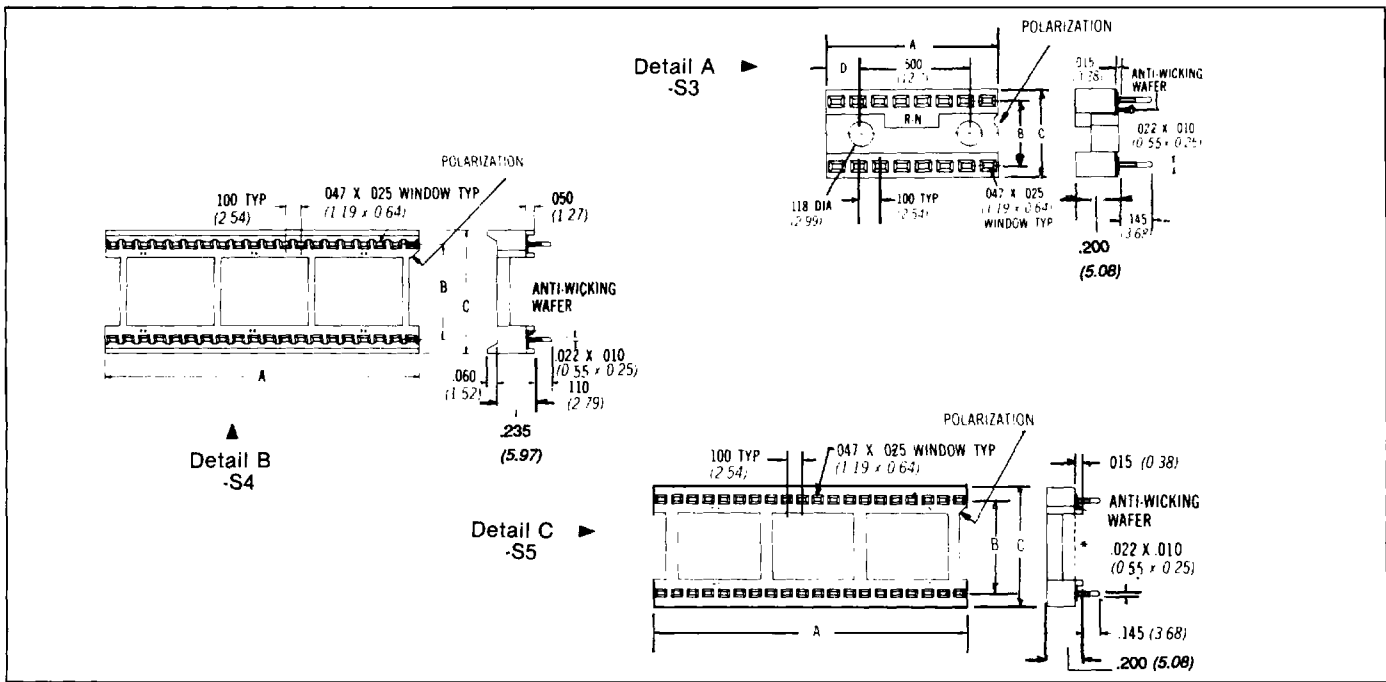
Dual Wipe Sockets

ICN Series

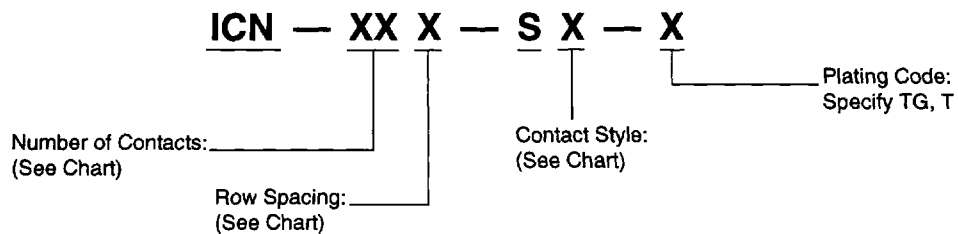
- General purpose, dual leaf side wipe contact provides high reliability
- Anti-wicking wafer prevents solder and flux wicking
- Open body design provides excellent cooling properties



SOCKETS



How To Order ICN Series



Part Numbers

Number of Contacts	Description Phosphor Bronze Contacts	Detail	Dimension A	Dimension B	Dimension C	Dimension D
6	ICN-063-S3-X	C	.295 (7.49)	.300 (7.62)	.405 (10.28)	—
8	ICN-083-S3-X	A	.395 (10.03)	.300 (7.62)	.405 (10.28)	—
14	ICN-143-S3-X	A	.695 (17.65)	.300 (7.62)	.405 (10.28)	.113 (2.87)
16	ICN-163-S3-X	A	.795 (20.19)	.300 (7.62)	.405 (10.28)	.163 (4.14)
18	ICN-183-S3-X	A	.895 (22.73)	.300 (7.62)	.405 (10.28)	.213 (5.41)
20	ICN-203-S3-X	A	.995 (25.27)	.300 (7.62)	.405 (10.28)	.263 (6.68)
24	ICN-246-S4-X	B	1.195 (30.35)	.600 (15.24)	.775 (19.68)	—
24	ICN-246-S5-X	C	1.195 (30.35)	.600 (15.24)	.705 (17.91)	—
28	ICN-286-S4-X	B	1.395 (35.43)	.600 (15.24)	.775 (19.68)	—
28	ICN-286-S5-X	C	1.395 (35.43)	.600 (15.24)	.705 (17.91)	—
32	ICN-326-S4-X	B	1.595 (40.51)	.600 (15.24)	.775 (19.68)	—
40	ICN-406-S4-X	C	1.995 (50.67)	.600 (15.24)	.775 (19.68)	—
40	ICN-406-S5-X	B	1.995 (50.67)	.600 (15.24)	.705 (17.91)	—
42	ICN-426-S4-X	B	2.095 (53.21)	.600 (15.24)	.775 (19.68)	—
48	ICN-486-S5-T	C	2.395 (60.83)	.600 (15.24)	.705 (17.91)	—

Materials:

Body: Black polyester, glass-filled
Contacts: Phosphor Bronze

Acceptable Pin Sizes:

Thickness: .015" (.38) maximum
Length: .080" - .150" (2.03-3.81)

Mounting Information:

PCB Hole: .035" ± .002" (.89 ± .05)
Location: Socket leads are offset .026" (.066) toward pin #1 from IC leads

Performance Characteristics:

Insertion Force: 5.1 oz*/contact
Withdrawal Force: 2.0 oz*/contact
 *Average of 2nd, 3rd, and 4th cycles using .011" flat pin similar to MIL-S-837340.
Capacitance: 1 picofarad maximum
Insulation Resistance: 5000 megohms minimum
Dielectric Withstanding Voltage: 500 volts AC
Current Rating: 1 Ampere
Flammability: UL 94V-0
Temperature Range: -65°C to + 105°C

Plating Description:

Suffix: **G** = 10 μinch (.254 μm) minimum Gold on contact area.
 Gold flash on terminal area.
T = 30 μinch (.762 μm) minimum hot dip Tin and wipe.

All options include: 50 μinch (1.27 μm) minimum Nickel underplate.